

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory | | User Part Number | | | | | | |
|-------------------------------------------|-----------------------------|------------------------------------------------------|-------------|-----------|------------|-----------|--|--|
| | | BAT721 | | | | | | |
| | | Part Description | | | | | | |
| | | Nexperia DHAM | Schottky | | | | | |
| Assembly reliability labs | | SMD package | | | | | | |
| Based on AEC-Q101 Test | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | | | | | | |
| | | Bake Tamb = 125 °C | 24 hours | | | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 810 | 58300 | 0 | | |
| | | MIL-STD-750-1 | | | | | | |
| | HTRB | M1038 Method A | | | | | | |
| | High Temperature Reverse | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage ^[1] | 1000 hours | 116 | 9280 | 0 | | |
| | | | | | | | | |
| | тс | JESD22-A104 | | | | | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 170 | 13600 | 0 | | |
| | | JESD22-A102 | | | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | | | |
| # A3 alt | Autoclave | Pressure = 205 kPa (29.7 psia) | 96 hours | 170 | 13600 | 0 | | |
| | | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | |
| # A2 alt | Temperature Reverse Bias | rated reverse voltage ^{[1], [2]} | 1000 hours | 170 | 13600 | 0 | | |
| | | MIL-STD-750 Method 1037 | | | | | | |
| | IOL | ton = toff, devices powered to insure ΔT_j = | | | | | | |
| # A5 | Intermittent Operating Life | | 1000 hours | 170 | 13600 | 0 | | |
| | | | | | | | | |
| | RSH | JESD22-A111 | | | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 130 | 3900 | 0 | | |
| | SD | | | | | - | | |
| # C10 | Solderability | J-STD-002 | | 363 | 3630 | 0 | | |

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Schottky | 9280 | 0 | 0.46 | 2.19E+09 |

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.